

ABSTRACT

First, through a coating step, a photolithography step and an etching step, a plurality of electrodes 142, 142, ... are formed on a base plate 141. Next, a resist layer 143b is formed on the base plate 141 so as to cover all of the electrodes 142, 142, ..., and by exposing and developing the resist layer 143b, a nozzle 103 having a super minute diameter is formed to stand with respect to the base plate 141 so as to make the resist layer 143b correspond to each electrode 142, and an in-nozzle passage is formed in each nozzle 103.